Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	6 X 6 X 0.8 (2.9 EP)
Lead Count	40
Terminal Finish	100 Sn
MS Number	MS000522D

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	**Yes**
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.40E-02	86.9	869100	48.42	484218
Thermosets	Epoxy & Phenol Resin	Proprietary	6.47E-03	12.8	127800	7.12	71204
Other inorganic materials	Carbon black	1333-86-4	1.57E-04	0.3	3100	0.17	1727
Subtotal			5.06 E-02	100.00	1000000	55.71	557148

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.28 E-02	97.5	975000	36.13	361251
Copper & its alloys	Iron	7439-89-6	7.91 E-04	2.35	23500	0.87	8707
Copper & its alloys	Zinc	7440-66-6	4.04 E-05	0.12	1200	0.04	445
Copper & its alloys	Phosphorus	7723-14-0	1.01 E-05	0.03	300	0.01	111
Subtotal			3.37 E-02	100.00	1000000	37.05	370514

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.37 E-05	100.0	1000000	0.04	371

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.15 E-03	100.0	1000000	2.37	23653

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.06 E-03	100.0	1000000	1.16	11636

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.86 E-03	100.0	1000000	3.15	31491

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.66 E-04	77.71	777100	0.40	4031
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.47 E-05	3.11	31100	0.02	161
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.47 E-05	3.11	31100	0.02	161
Other organic materials	Butyrolactone, gamma-	96-48-0	1.47 E-05	3.11	31100	0.02	161
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.47 E-05	3.11	31100	0.02	161
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.47 E-05	3.11	31100	0.02	161
Other organic materials	Organosilane	TS ref# 10001	1.47 E-05	3.11	31100	0.02	161
Other inorganic materials	Copper(II) oxide	1317-38-0	1.47 E-05	3.11	31100	0.02	161
Other organic materials	Epoxy resin modifier	TS ref# 10038	2.45 E-06	0.52	5200	0.00	27
Subtotal			4.72 E-04	100.0	1000000	0.52	5187

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.09 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary